

# Lonten N-channel 30V, 100A, 1.6mΩ Power MOSFET

### **Description**

These N-Channel enhancement mode power field effect transistors are using split gate trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

#### **Features**

- 30V,100A,  $R_{DS(on),max} = 1.6 \text{m}\Omega @V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- ♦ 100% EAS Guaranteed
- ◆ Green device available

### **Applications**

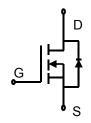
- Motor Drives
- ◆ UPS
- ◆ DC-DC Converter

## **Product Summary**

 $\begin{array}{ll} V_{DSS} & 30V \\ R_{DS(on),max} @ V_{GS} \text{=} 10V & 1.6 m\Omega \\ I_D & 100A \end{array}$ 

#### **Pin Configuration**





N-Channel MOSFET



#### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	30	V
Continuous drain current ( T <sub>C</sub> = 25°C ) <sup>1)</sup>		100	A
Continuous drain current ( T <sub>C</sub> = 100°C ) <sup>1)</sup>	- I <sub>D</sub>	63	А
Pulsed drain current <sup>2)</sup>	I <sub>DM</sub>	350	А
Gate-Source voltage	V <sub>GSS</sub>	±20	V
Avalanche energy <sup>3)</sup>	Eas	151	mJ
Power Dissipation ( T <sub>C</sub> = 25°C )	PD	62.5	W
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C
Operating Junction Temperature Range	TJ	-55 to +150	°C

#### **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R <sub>eJC</sub>	2.0	°C/W
Thermal Resistance Junction-to-Ambient	R <sub>0JA</sub>	50	°C/W

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**Package Marking and Ordering Information** 

Device	Device Package	Marking
LSGN03R016WB	DFN5X6	03R016WB

#### Electrical Characteristics T<sub>1</sub> = 25°C unless otherwise noted

Electrical Characteristics T <sub>J</sub> = 25°C unless otherwise noted						
Parameter	Symbol	mbol Test Condition		Тур.	Max.	Unit
Static characteristics						•
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, I <sub>D</sub> =250uA	30			V
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1.2	1.6	2.2	V
Drain-source leakage current	I <sub>DSS</sub>	V <sub>DS</sub> =30 V, V <sub>GS</sub> =0V, T <sub>J</sub> = 25°C			1	μA
Gate leakage current, Forward	I <sub>GSSF</sub>	V <sub>GS</sub> =20 V, V <sub>DS</sub> =0 V			100	nA
Gate leakage current, Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> =-20 V, V <sub>DS</sub> =0 V			-100	nA
Drain-source on-state resistance	_	V <sub>GS</sub> =10 V, I <sub>D</sub> =20 A		1.3	1.6	mΩ
	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5 V, I <sub>D</sub> =20 A		1.9	2.5	mΩ
Forward transconductance	g <sub>fs</sub>	V <sub>DS</sub> =5V , I <sub>D</sub> =20A		36.5		S
Dynamic characteristics						
Input capacitance	C <sub>iss</sub>	45,47,4		3421		pF
Output capacitance	Coss	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ F = 1 MHz		1914		
Reverse transfer capacitance	C <sub>rss</sub>	- F = TMHZ		195		
Turn-on delay time	t <sub>d(on)</sub>			10.4		
Rise time	tr	V <sub>DD</sub> = 15V,V <sub>GS</sub> =10V, I <sub>D</sub> = 20A		6.0		ns
Turn-off delay time	t <sub>d(off)</sub>	R <sub>G</sub> =3.3Ω		56.3		1
Fall time	t <sub>f</sub>	_		8.1		
Gate resistance	Rg	V <sub>GS</sub> =0 V,V <sub>DS</sub> =0 V, F=1MHz		1.1		Ω
Gate charge characteristics	•					
Gate to source charge	Q <sub>gs</sub>	V 45V L 00A		9.8		
Gate to drain charge	Q <sub>gd</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =20A,		6.5		nC
Gate charge total	Qg	- V <sub>GS</sub> = 10 V		53		
Drain-Source diode characteristic	cs and Maxi	mum Ratings				
Continuous Source Current	Is				100	Α
Pulsed Source Current <sup>4)</sup>	I <sub>SM</sub>				300	Α
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A, T <sub>J</sub> =25℃			1.2	V

#### Notes:

- 1: The maximum junction current rating is package limited.
- 2: Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3:  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =55A, Starting  $T_J$ =25  $^{\circ}$ C.
- 4: Pulse Test: Pulse Width  $\leq 300~\mu$  s, Duty Cycle  $\leq 2\%$  .
- 5: Guaranteed by design, not subject to production.

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### **Electrical Characteristics Diagrams**

Figure 1. Typ. Output Characteristics

V<sub>GS</sub>=10V
V<sub>GS</sub>=6V
V<sub>GS</sub>=4.5V
V<sub>GS</sub>=3.5V
V<sub>GS</sub>=3.5V
V<sub>GS</sub>=3V
V<sub></sub>

Figure 2. Transfer Characteristics

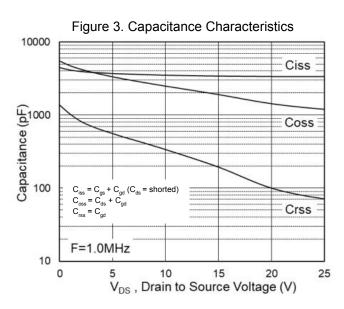
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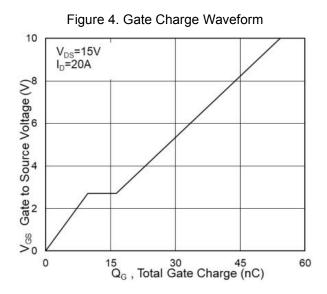
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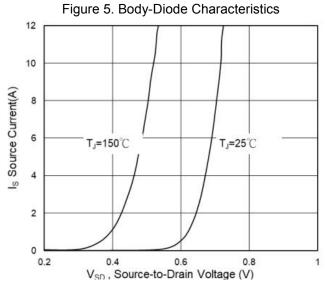
T=125°C

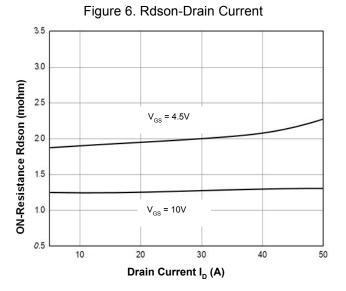
T=25°C

Gate-source voltage V<sub>GS</sub> (V)









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Figure 7. Rdson-Junction Temperature(°C)

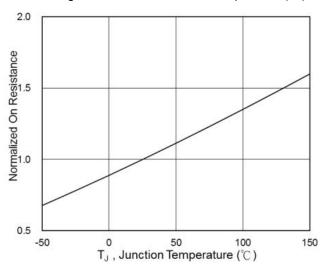


Figure 8. V<sub>GS(th)</sub>-Junction Temperature(°C)

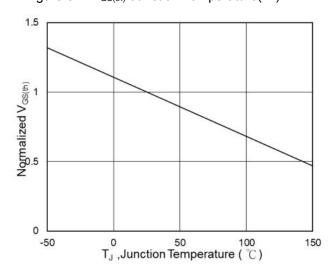


Figure 9. On-Resistance vs. Gate-to-Source voltage

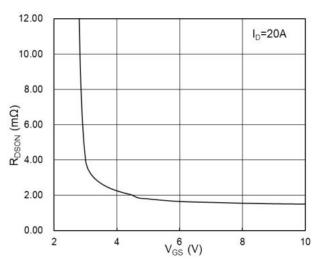


Figure 10. Maximum Safe Operating Area

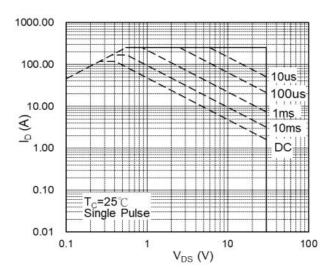
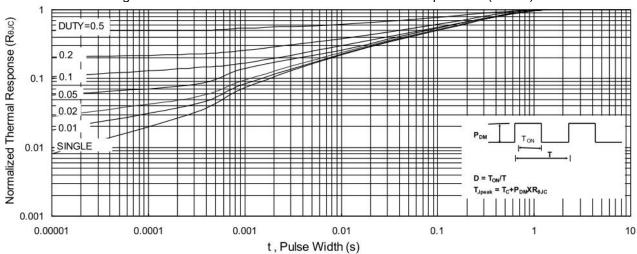


Figure 11. Normalized Maximum Transient Thermal Impedance (RthJC)

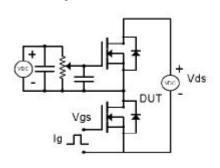


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#### **Test Circuit & Waveform**

Figure 12. Gate Charge Test Circuit & Waveform



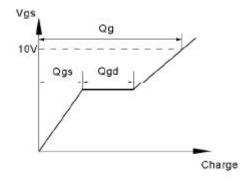
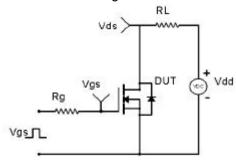


Figure 13. Resistive Switching Test Circuit & Waveforms



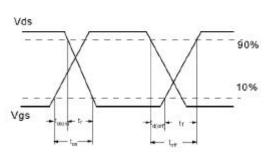
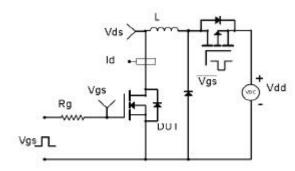


Figure 14. Unclamped Inductive Switching (UIS) Test Circuit & Waveform



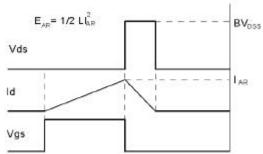
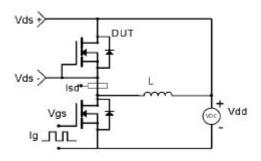
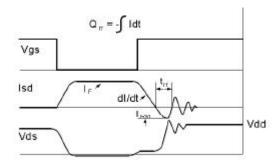


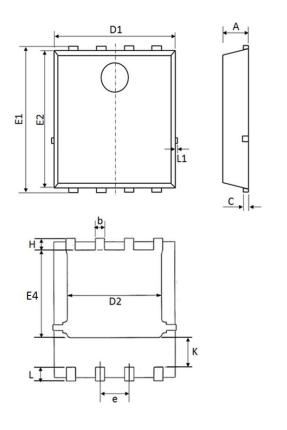
Figure 15. Diode Recovery Circuit & Waveform





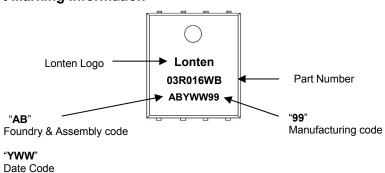


# **Mechanical Dimensions for DFN5×6**



COMMON DIMENSIONS							
SYMBOL	MILLIMETERS			INCHS			
	MIN	NOM	MAX	MIN	NOM	MAX	
А	1	1.1	1.2	0.039	0.043	0.047	
b	0.3	0.4	0.5	0.012	0.016	0.020	
С	0.154	0.254	0.354	0.006	0.010	0.014	
D1	5	5.2	5.4	0.197	0.205	0.213	
D2	3.8	4.1	4.25	0.150	0.161	0.167	
E1	5.95	6.15	6.35	0.234	0.242	0.250	
E2	5.66	5.86	6.06	0.223	0.231	0.239	
E4	3.52	3.72	3.92	0.139	0.146	0.154	
е	1.27 BSC			0.050 BSC			
Н	0.4	0.5	0.6	0.016	0.020	0.024	
L	0.5	0.6	0.7	0.020	0.024	0.028	
L1	-	-	0.12	-	-	0.005	
К	1.14	1.29	1.44	0.045	0.051	0.057	

# **DFN5×6 Part Marking Information**





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